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Electronics in Our Daily Life Today and Packaging Trends Influencing the Future

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ELECTRONICS IN OUR DAILY LIFE TODAY AND PACKAGING TRENDS INFLUENCING THE FUTURE

April 14th, 2009

Dr. S. Manian Ramkumar

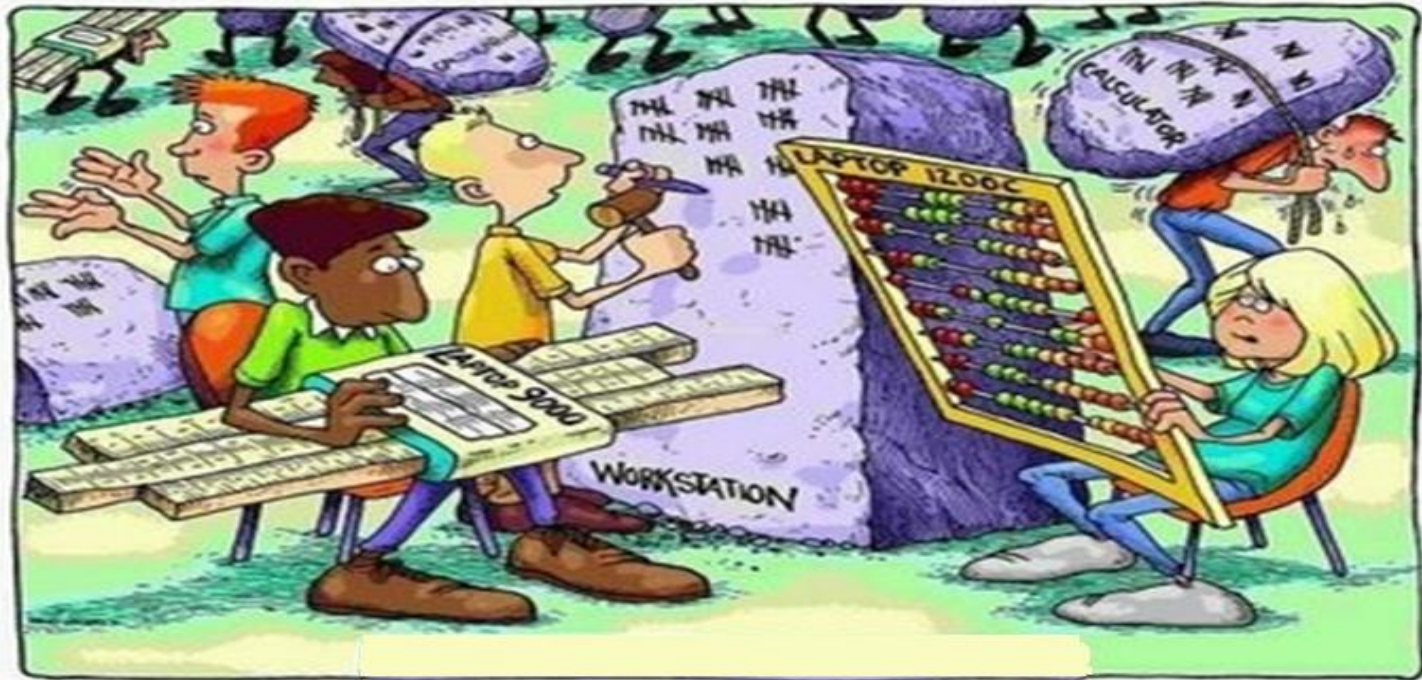
Agenda

2

- **Electronics**
 - Imagine a world without Electronics
 - Influence on lifestyle
 - Markets and trends
- **Electronics Packaging Levels and Trends**
- **Electronics Assembly**
- **Microsystems and Medical Electronics**
- **The Center for Electronics Manufacturing and Assembly @ RIT**
 - Education , Industry Training and Scholarship
- **Q & A session**

World Without Electronics...

3



Influence of Electronics Today

4



R.I.T *Faculty Scholars Series* April 14th, 2009

Electronics is Almost Everywhere

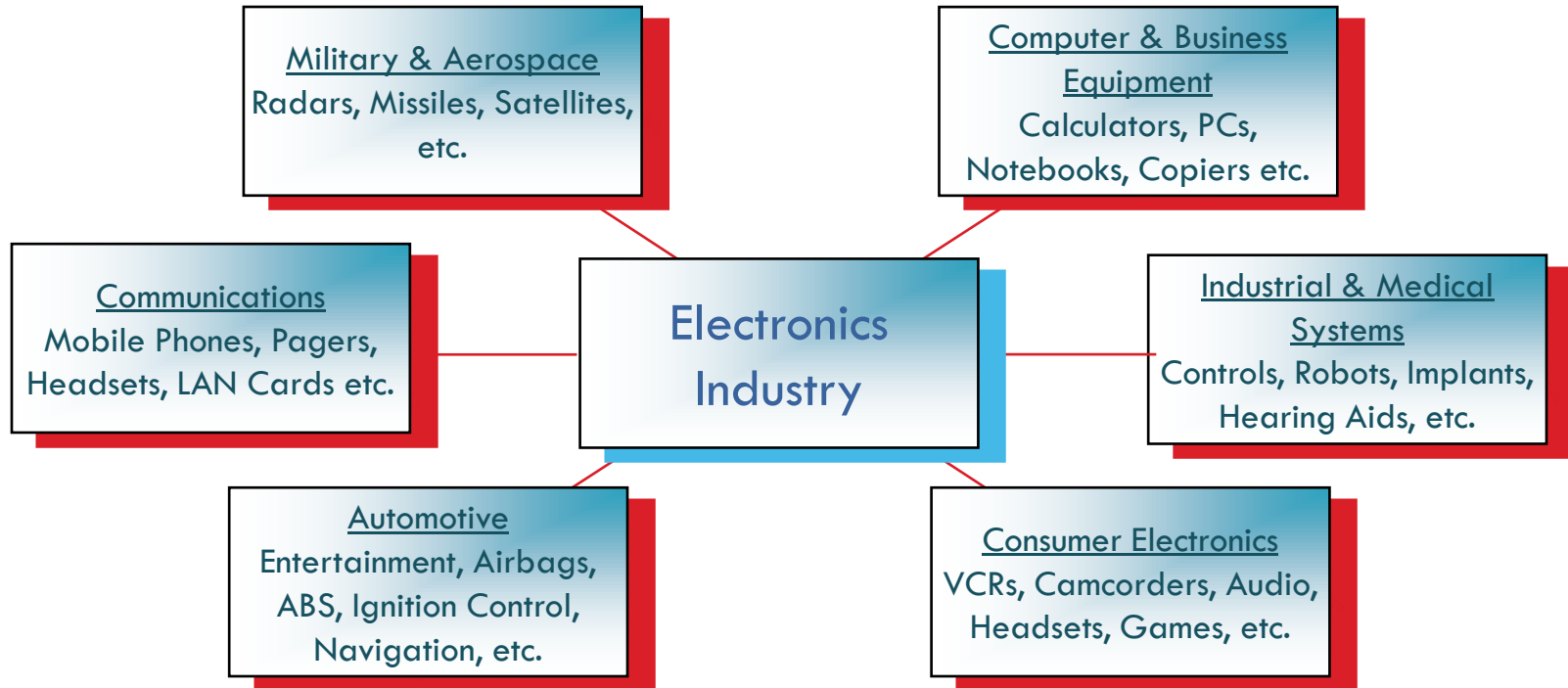
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April 14th, 2009

The Electronics Industry



The Market

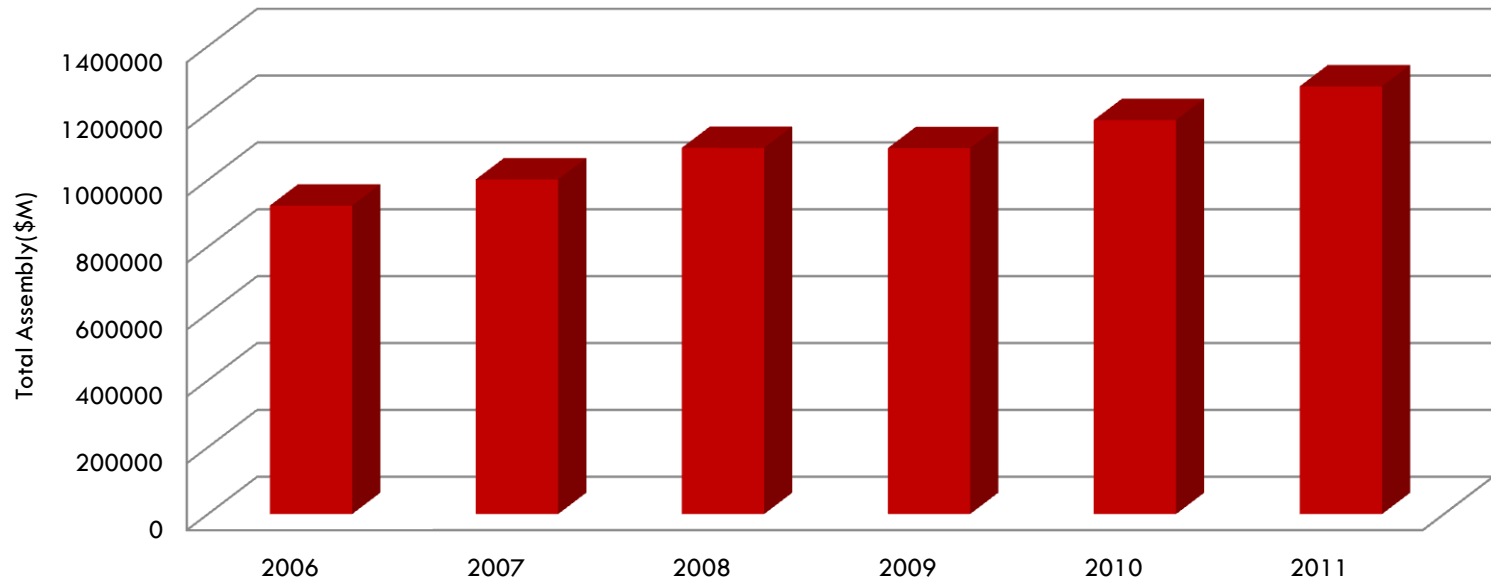
7

- **Electronic Industry**
 - Largest manufacturing industry in the world
 - Growing twice as fast as the global economy
 - Very dynamic, propelled by constant technological change
 - \$3.2 Trillion by 2012
 - Major US markets are medical, defense and aerospace electronics

Global Market Trend for Electronic Product Assembly

8

Market Trend



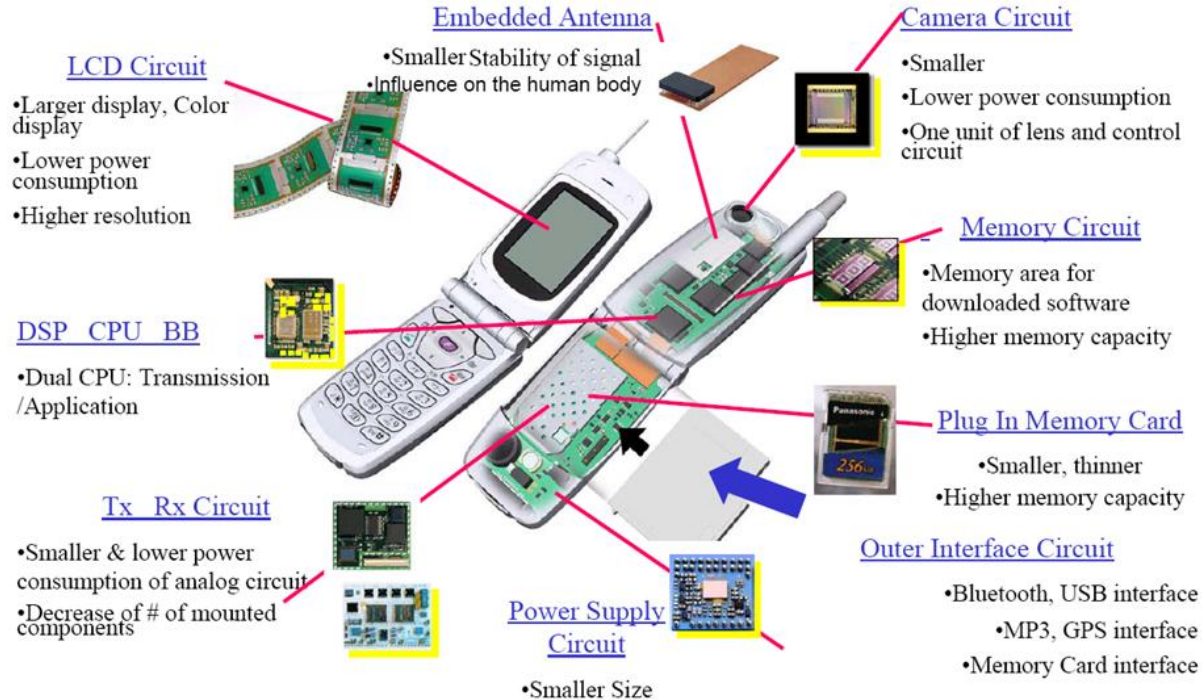
Continuous Miniaturization

9



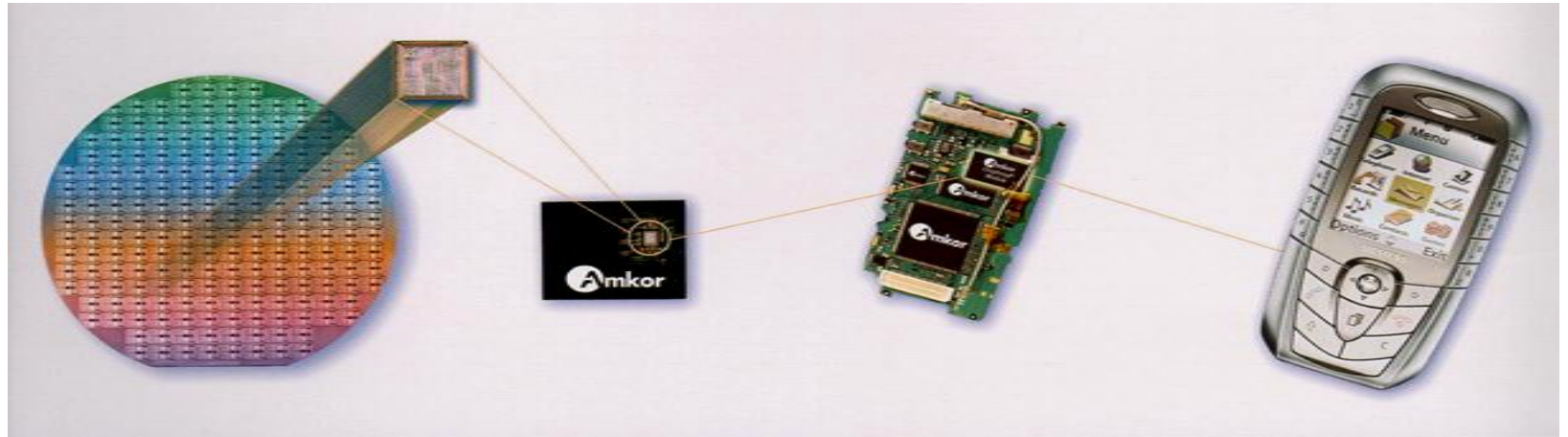
A Look Inside a Cell Phone

10



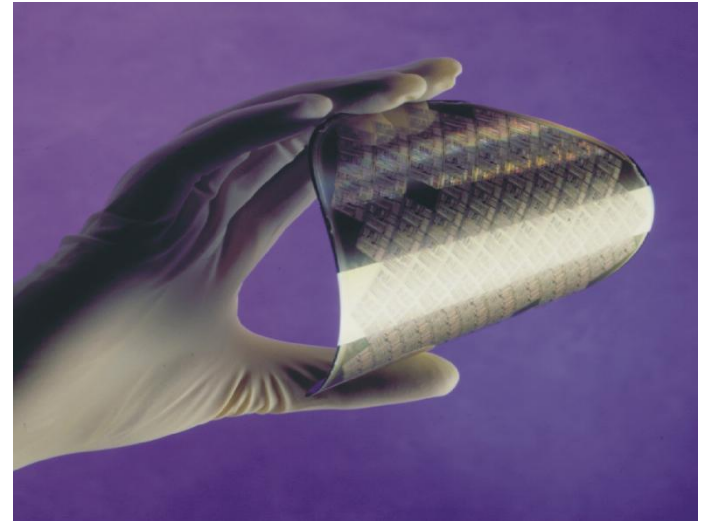
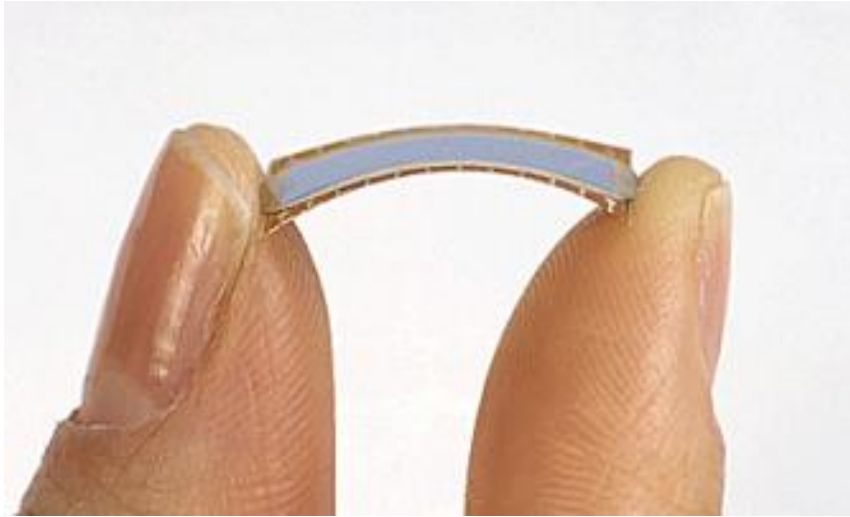
Electronics Package - Levels

11



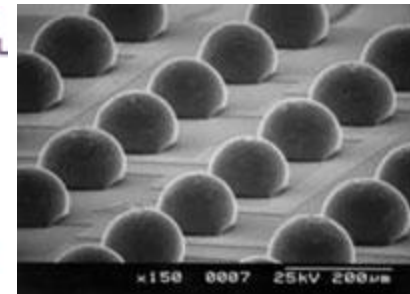
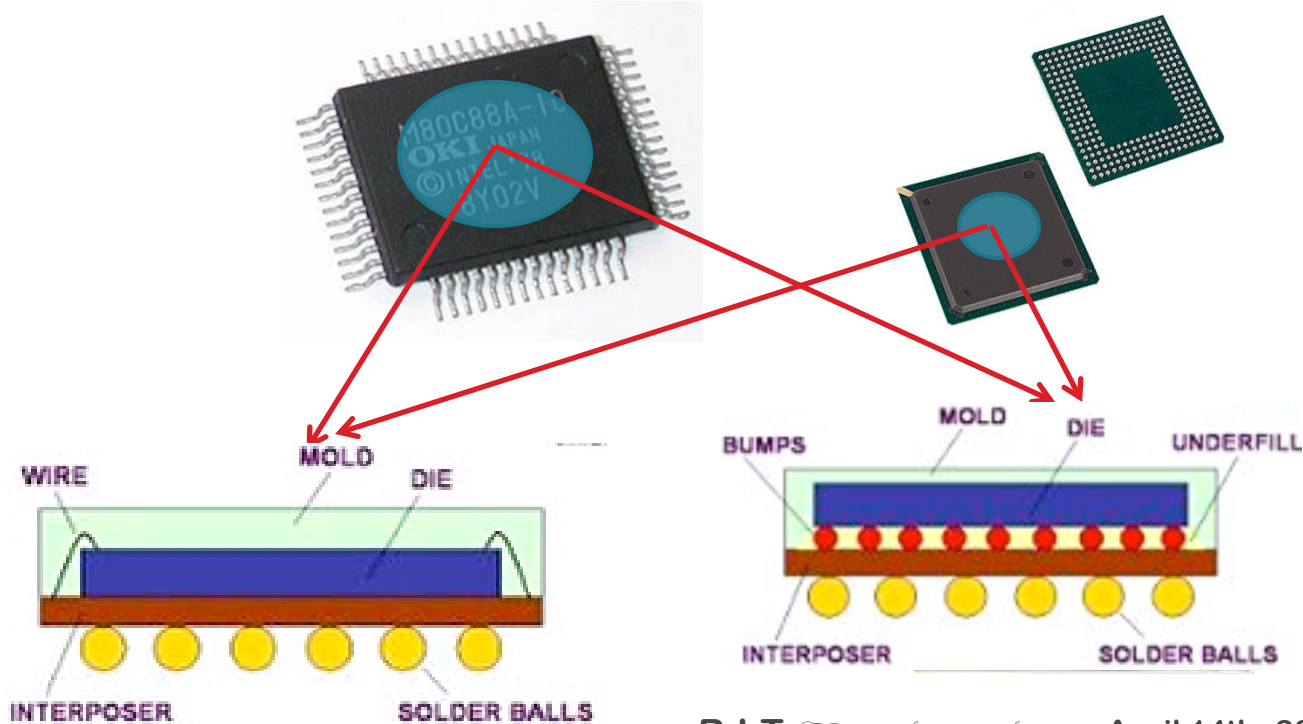
Flexible Silicon

12



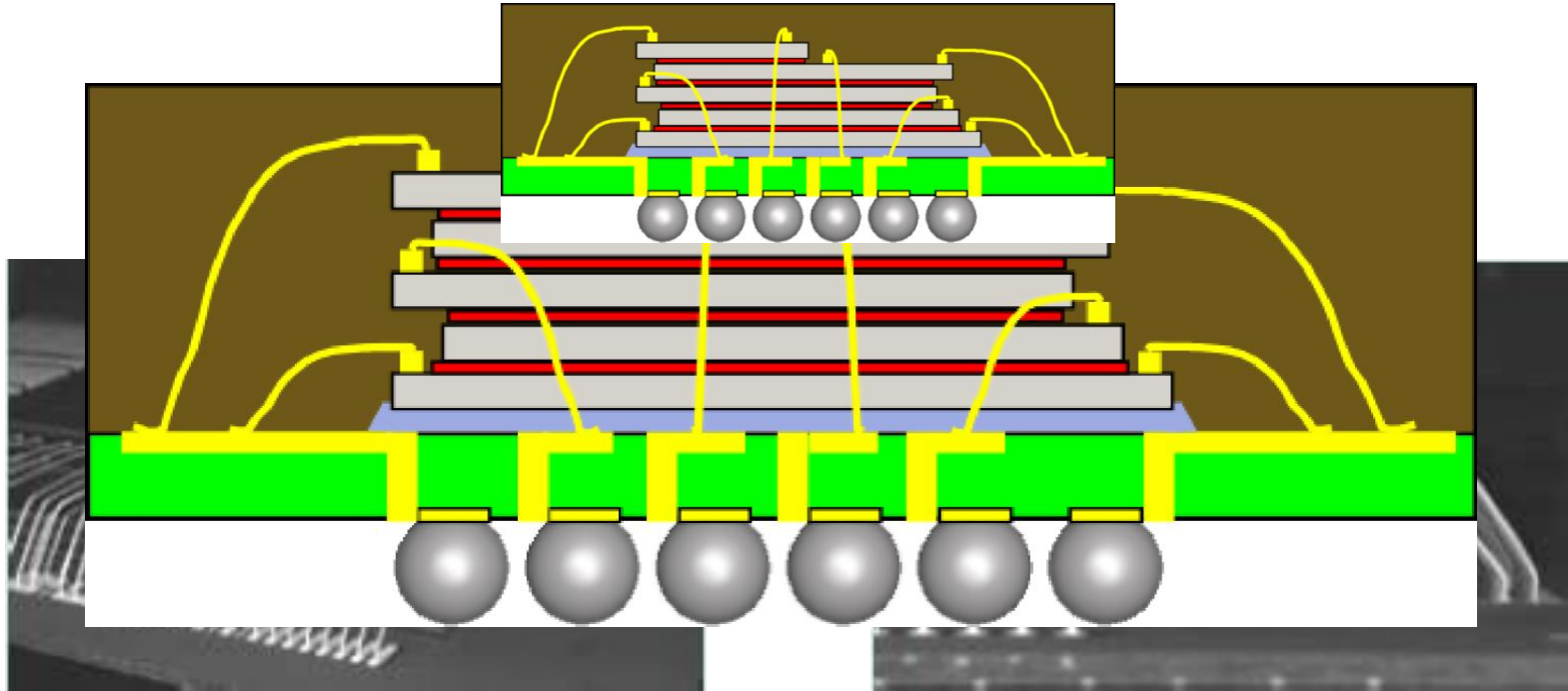
Component Level Package

13



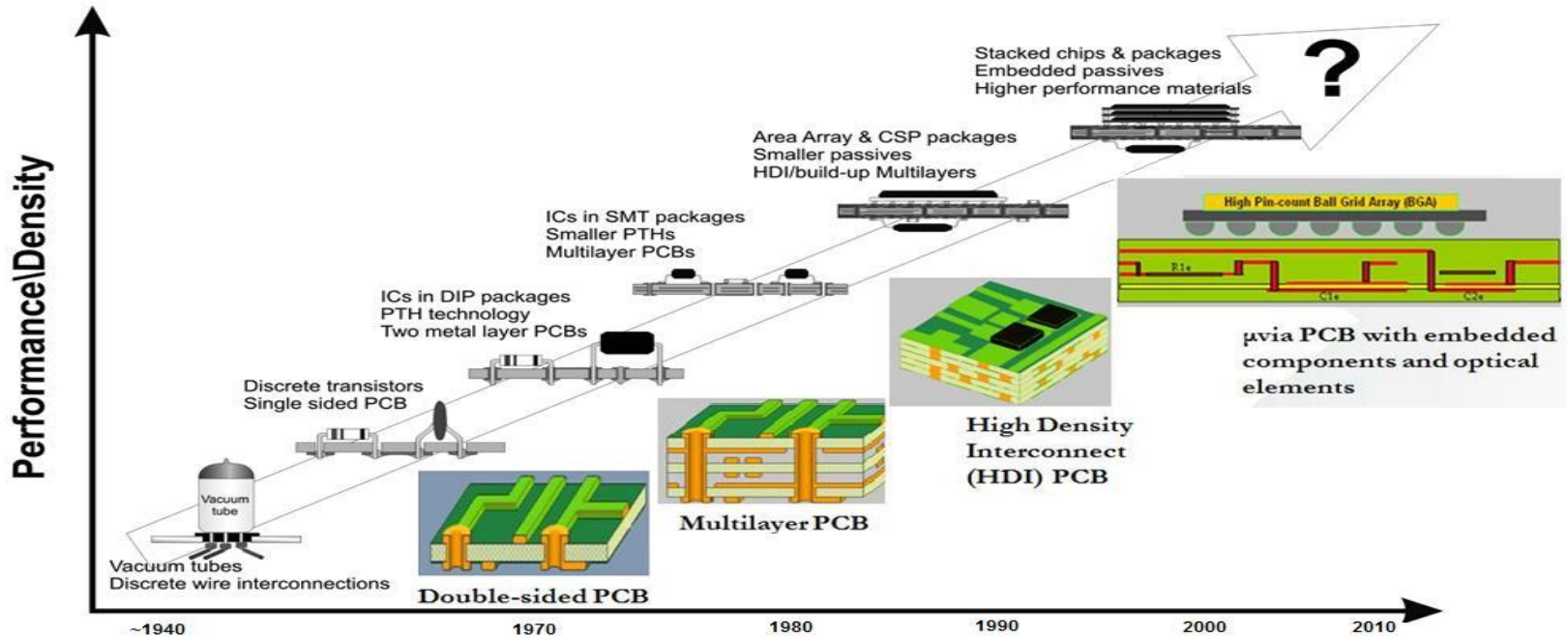
Silicon Chip Stacking

14



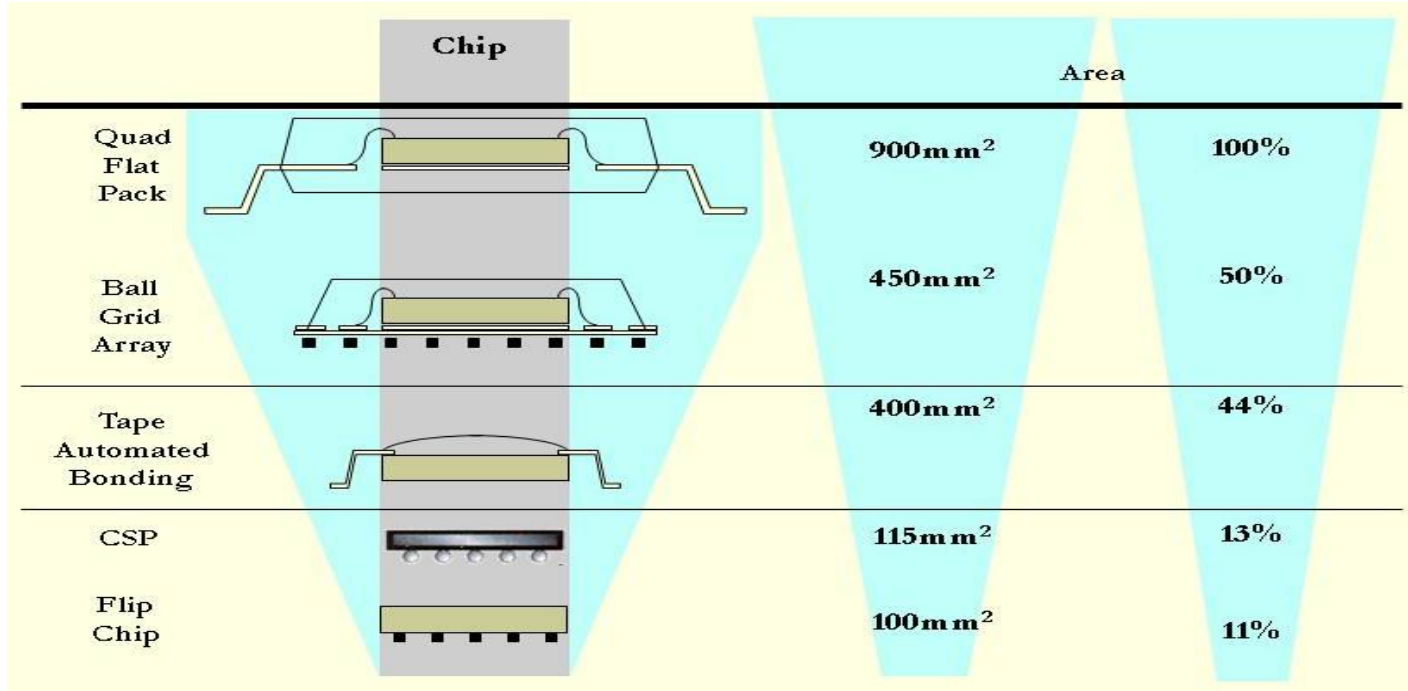
Packaging – Road Map

15



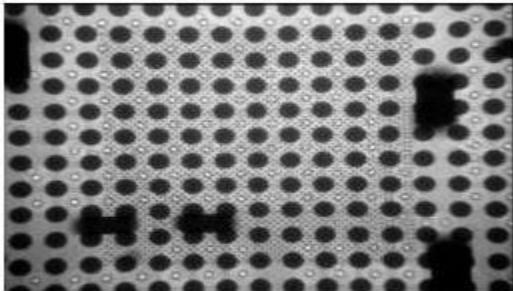
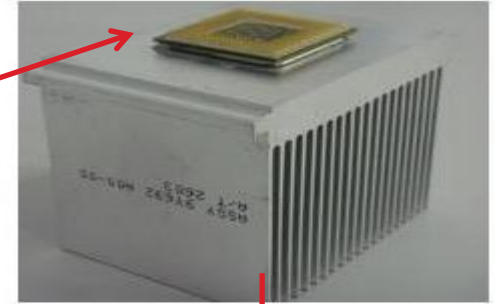
Size Reduction

16



Inside a Computer

17



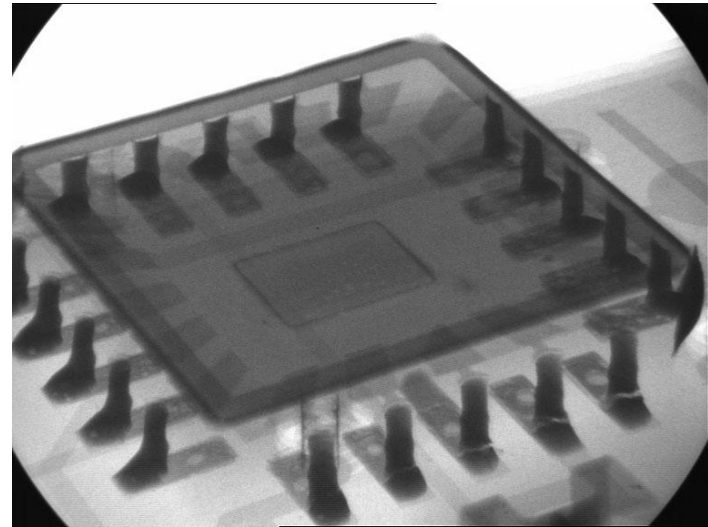
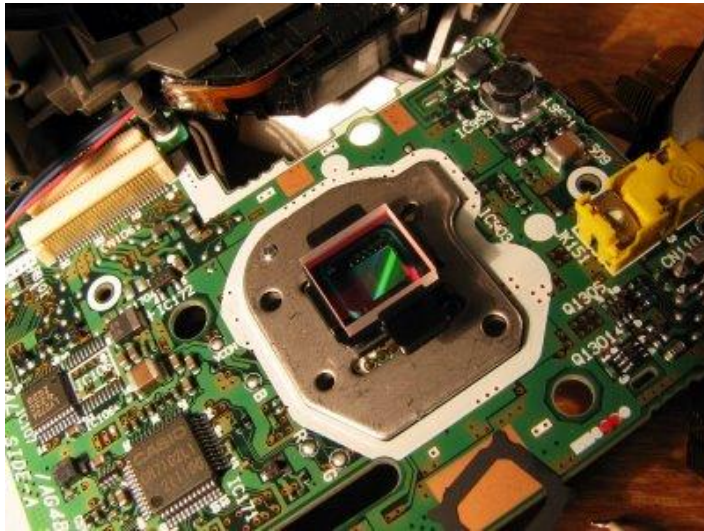
Inside a Laptop

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Digital Camera

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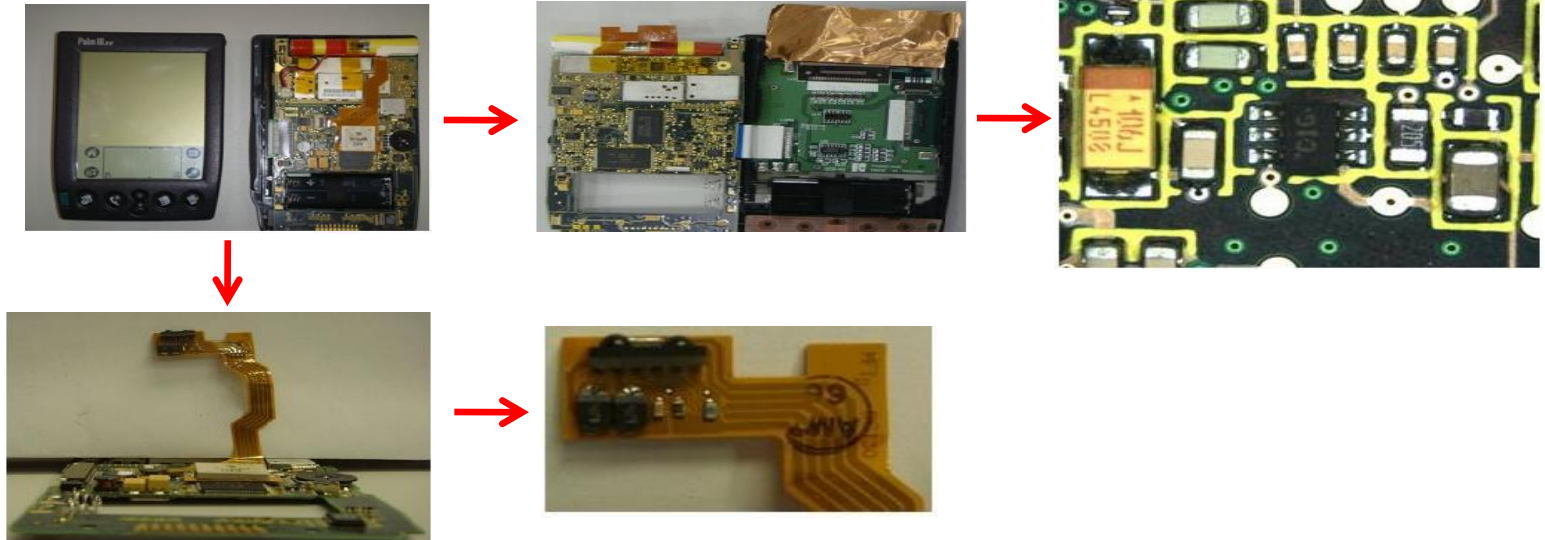
Inside an iPod Shuffle

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Inside a Palm Pilot

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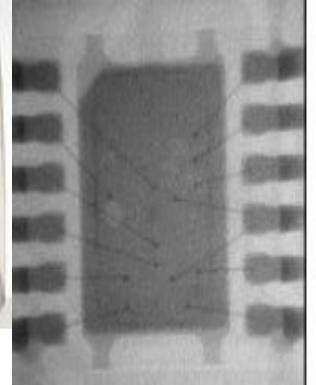


Form Factor Reduction

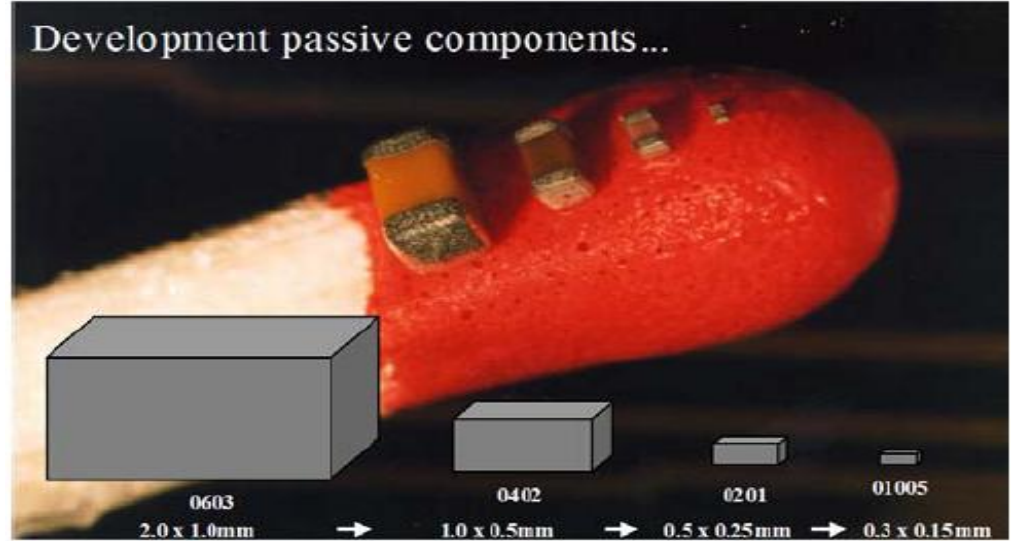
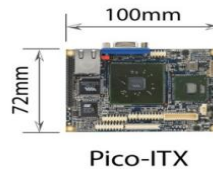
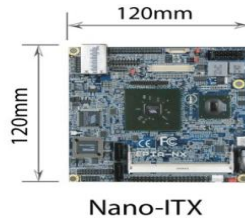
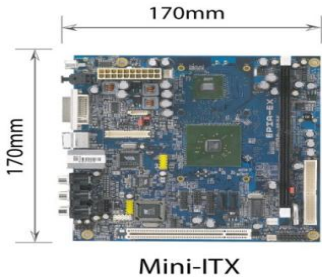
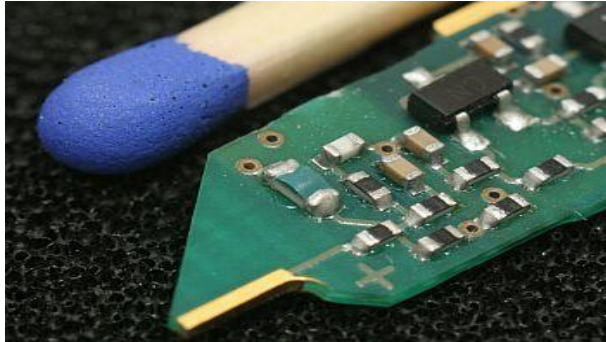
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- Size
- Weight
- Circuit Density
- Features
- Battery
- Antenna

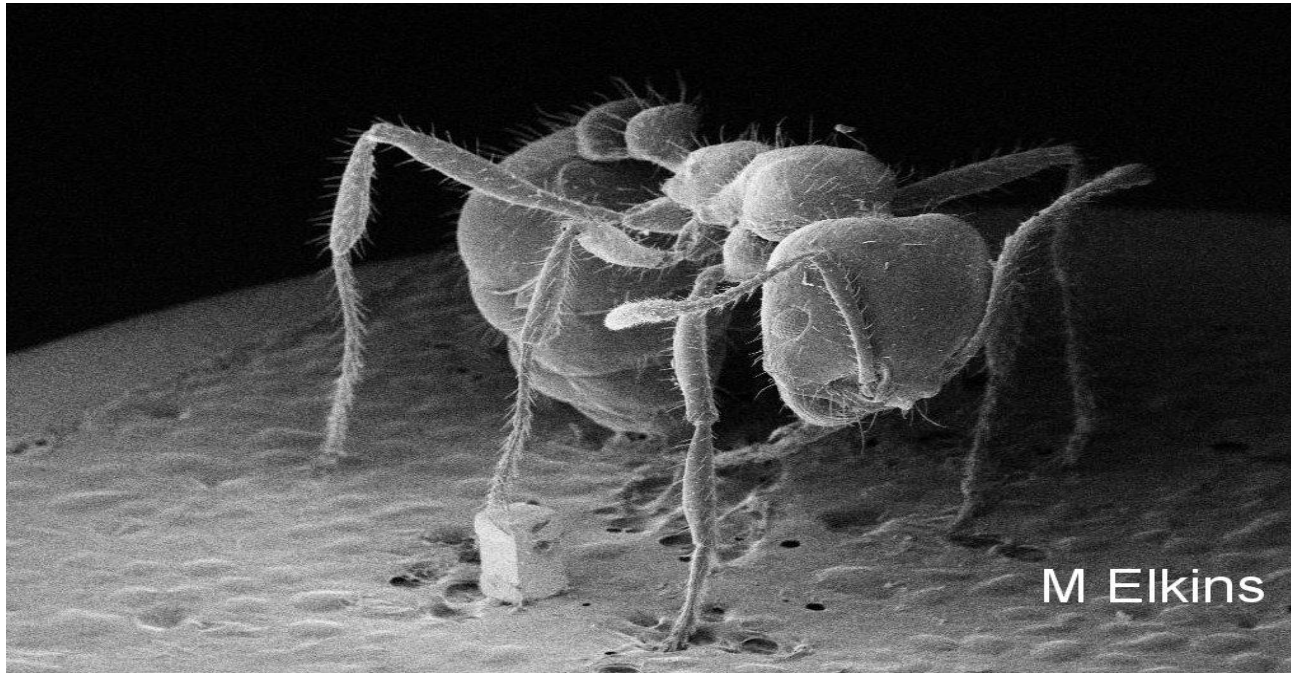


Product Miniaturization



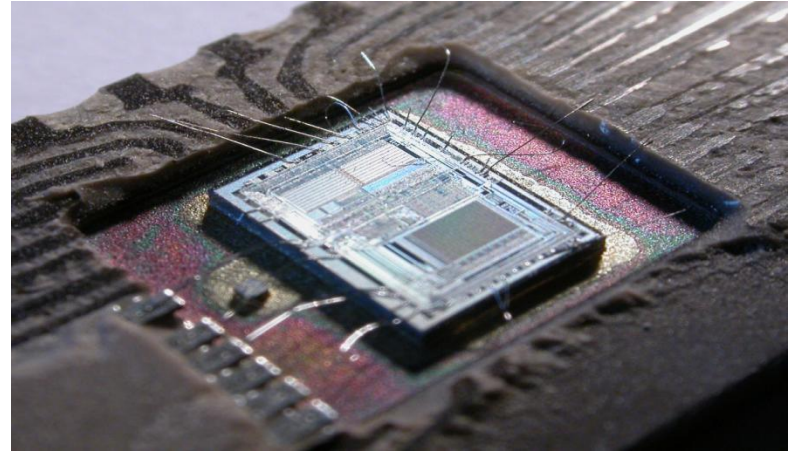
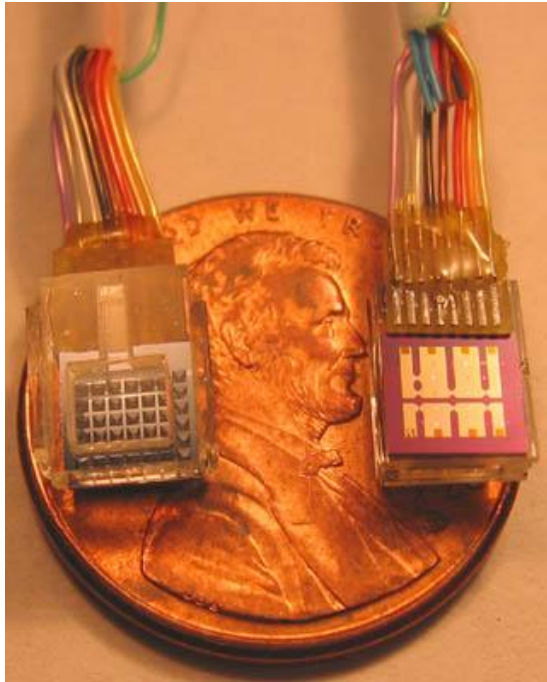
Component Miniaturization

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Product Miniaturization

25



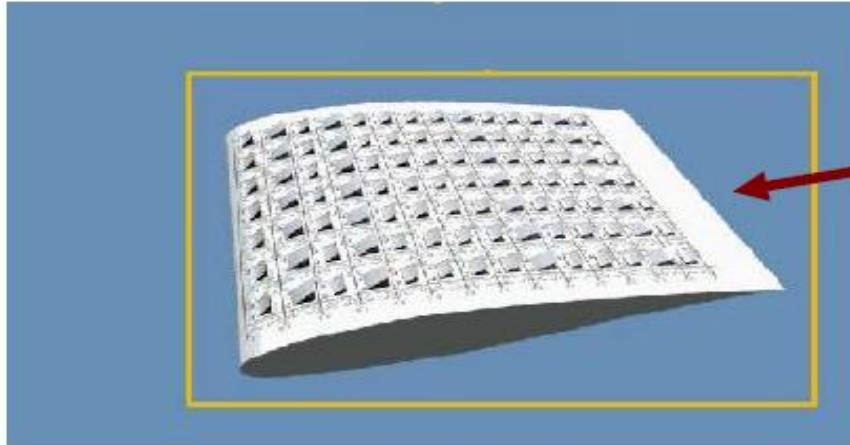
PCB Assembly Process

26



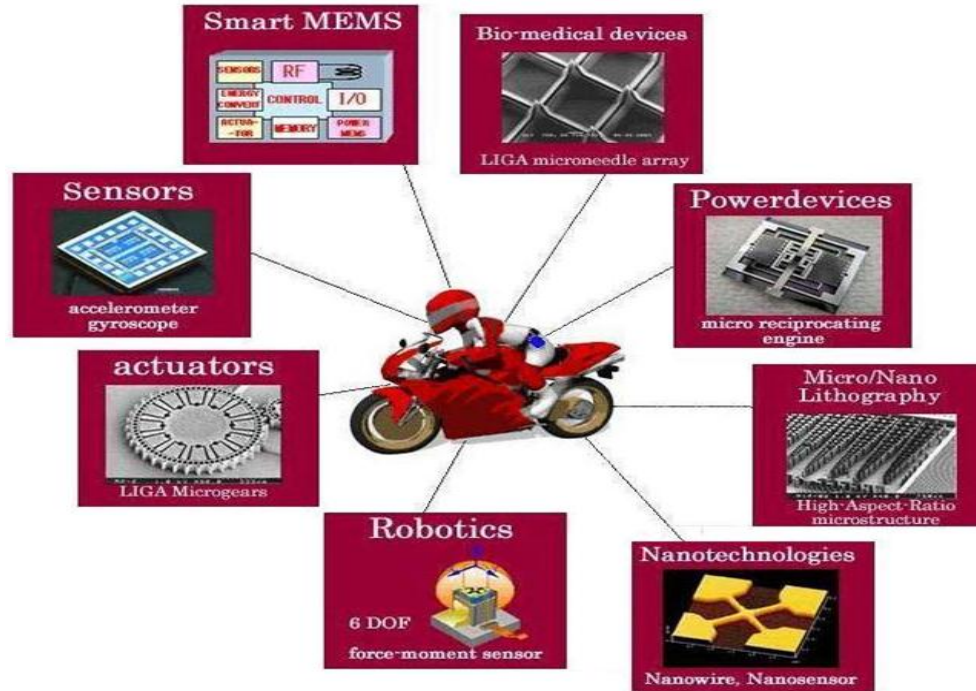
MEMS Piezo Actuators for Macro Actuation

27



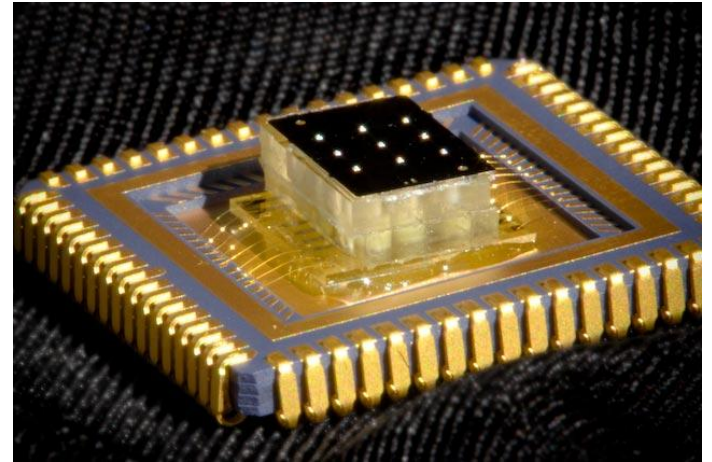
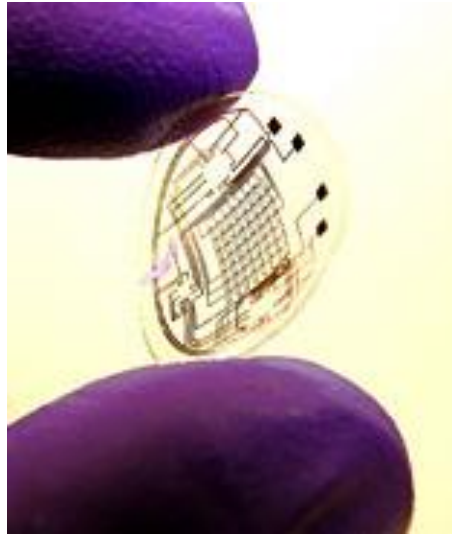
MEMS - Applications

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Medical Electronics

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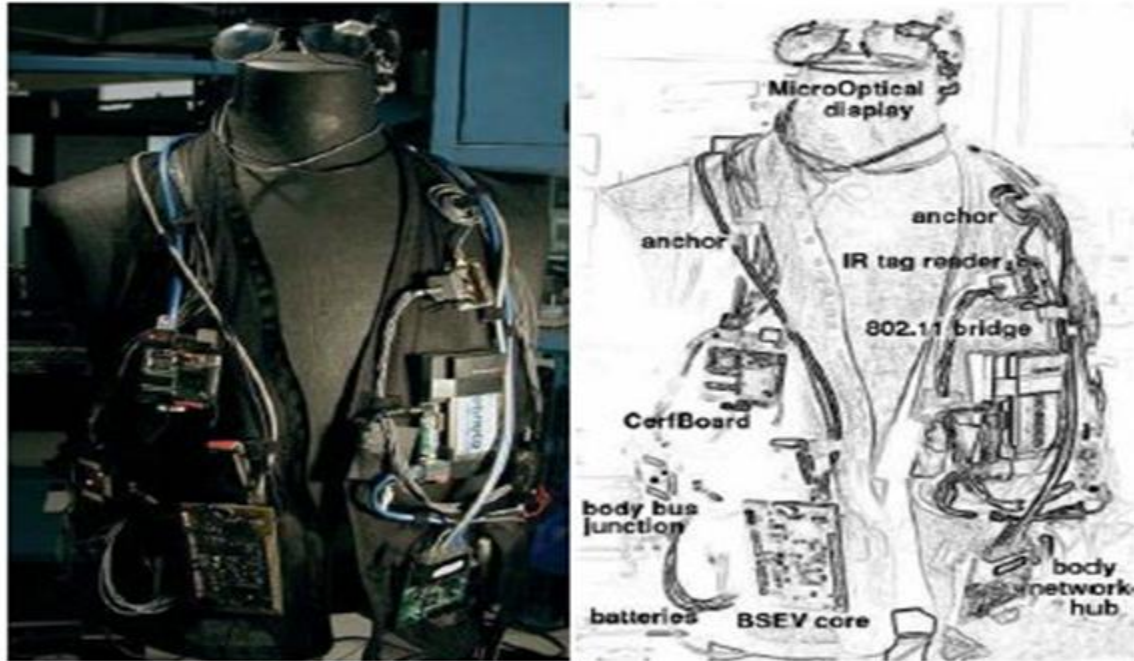


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Networked Body Monitoring Systems

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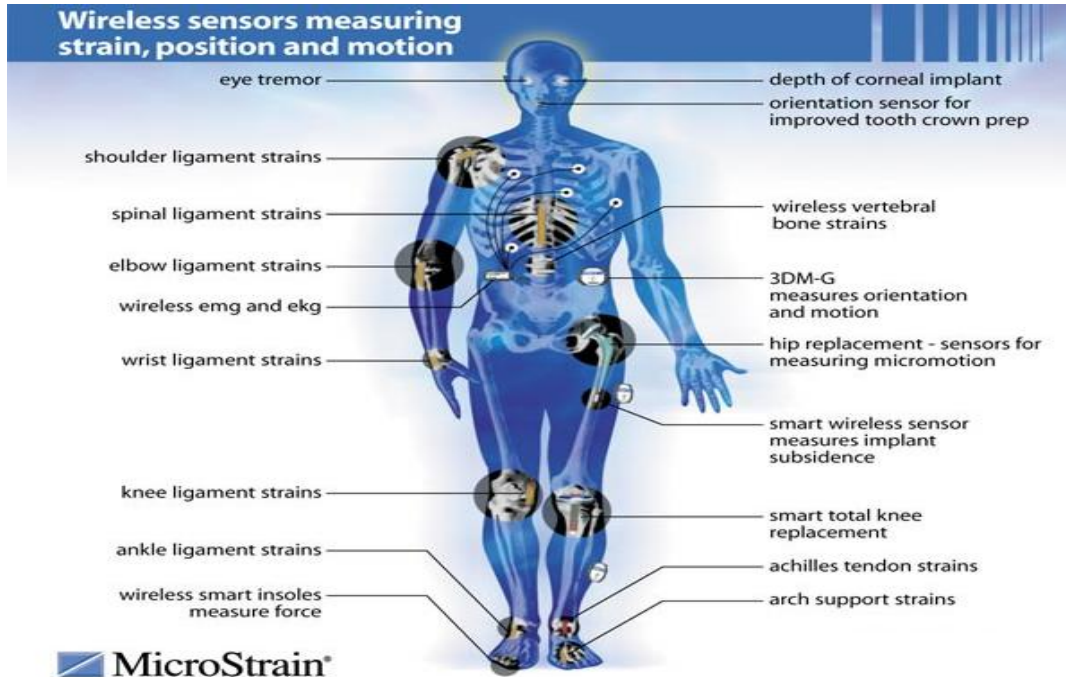


MEMS based Robotic Surgery

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Implantable Strain Sensors



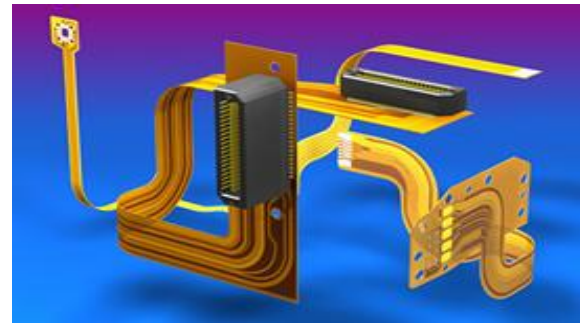
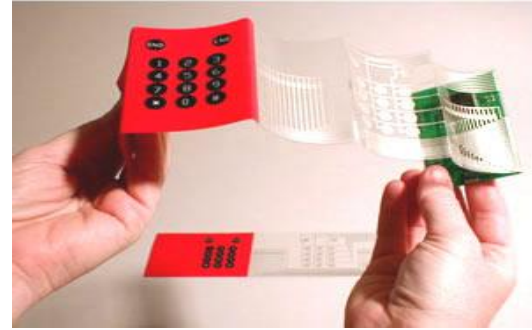
Wearable Electronics

33



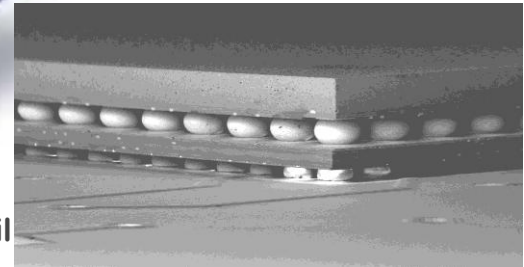
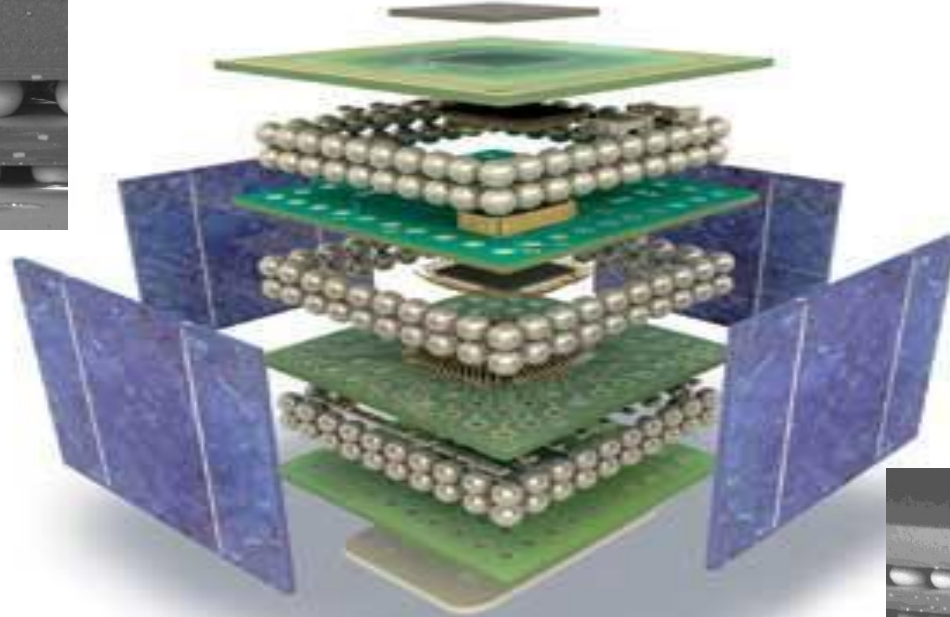
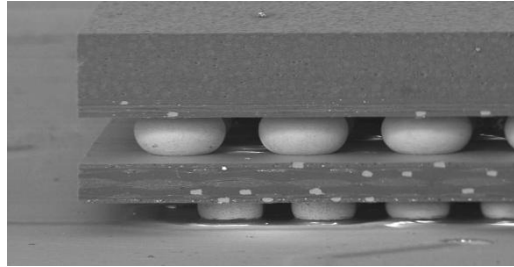
Flexible and Molded Substrates

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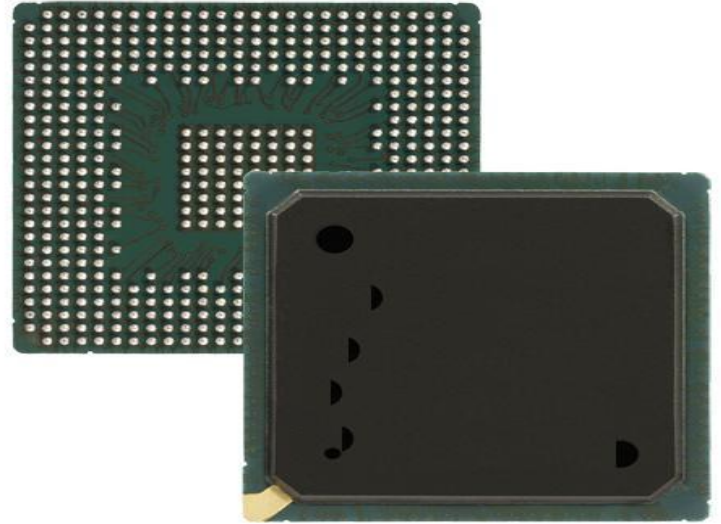
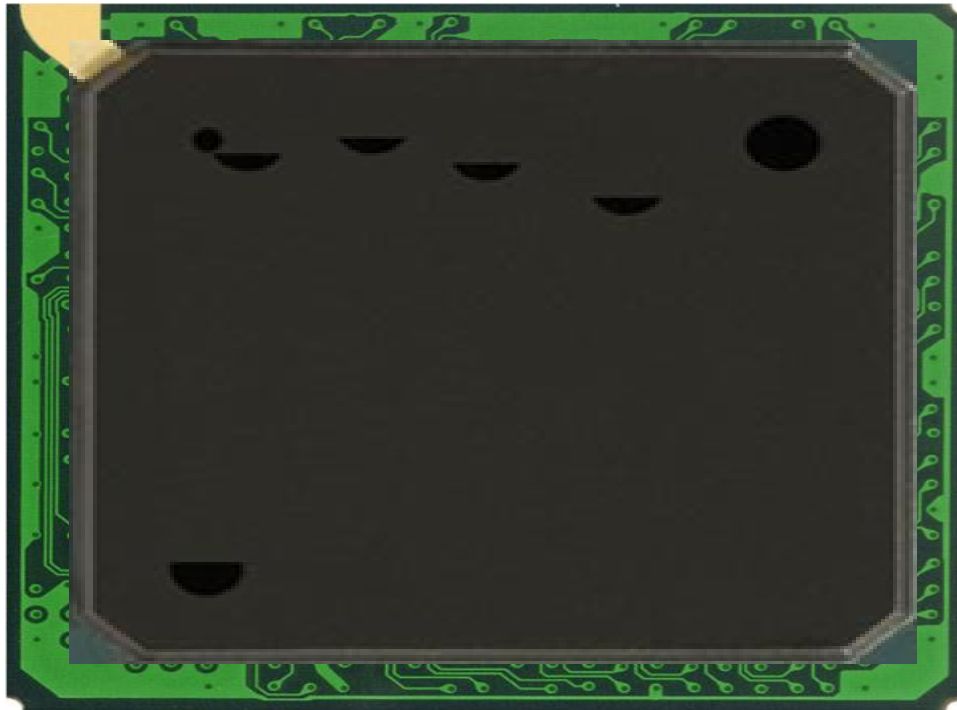
3-D Packages

35



Multi Chip Modules (MCM)

36



Technology Drivers

37

- ❑ **Small form factor**
- ❑ **Faster and miniaturized Components**
- ❑ **Flexible Electronics**
- ❑ **Increased quality and reliability**
- ❑ **Efficient Thermal Management**
- ❑ **Faster time to market**
- ❑ **High Product variety**
- ❑ **Low Cost**

CENTER FOR ELECTRONICS MANUFACTURING AND ASSEMBLY (CEMA)

*“QUICK TURNAROUND, VALUE ADDED,
ELECTRONICS PACKAGING SERVICES TO
COMPANIES”*

Scholarship @ CEMA

39

- **Scholarship of Discovery**
 - Applied research on materials and processes
- **Scholarship of Teaching**
 - Educational program for RIT undergraduate and graduate students
 - Onsite or on campus training for industry
 - Workshops and professional development courses at conferences
- **Scholarship of Application**
 - Analytical evaluation of PCB assemblies
 - Process development, optimization and implementation
- **Scholarship of Integration**
 - Product development and prototype assembly

CEMA – Facilities & Equipment

40



CEMA - Donors

41



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CEMA - Faculty Collaborators

42

- ❑ **Dr. Carol Romanowski (Center for Multidisciplinary Studies)**
- ❑ **Dr. Scott Anson (CAST – MMET/PS)**
- ❑ **Dr. Robert Parody (Center for Quality and Applied Statistics)**
- ❑ **Dr. Robert Bowman (College of Engineering – EE)**
- ❑ **Dr. Joseph Voelkel (Center for Quality and Applied Statistics)**
- ❑ **Dr. Warren Koontz (CAST – ECTET)**
- ❑ **Dr. P. Venkatraman (College of Engineering – ME)**
- ❑ **Prof. Charles Swain (CAST – ECTET)**
- ❑ **Prof. TiLin Lu (CAST – MMET/PS)**

CEMA - Student Placement

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- Aurora Opticals
- Benchmark Electronics
- Tyco Electronics
- Hughes Electronics
- Qualcomm
- Flextronics International
- Plexus
- Marquardt Switches
- TRW Automotive
- Honeywell
- Vansco Electronics
- Eaton Corporation
- Anaren Microwave
- REDCOM Laboratories
- IEC Electronics
- Tektronix
- Harris RF Communications
- SoPark Corporation
- Intel
- Universal Instruments
- Continental Automotive Electronics
- Delphi Electronics
- Lockheed Martin

CEMA - Significant Influence Locally

44

- Ashly Audio
- Biophan Technologies
- D3 Engineering
- Delphi Electronics
- Eastman Kodak Company
- Hand Held Products (Presently Honeywell)
- Harris Corporation
- Hover-Davis
- Illumitech
- Insight Avionics
- Lumetrics
- L-3 Communications
- Marquardt Switches
- Moog
- Nexpress Solutions
- Performance Technologies
- REDCOM Laboratories
- SCJ Associates
- Sopark
- SenDec
- Spectracom
- Surmotech
- TREK Inc.
- Vincent Associates
- Windsor Manufacturing Co.
- Xerox

Future with Electronics

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Thank you !

